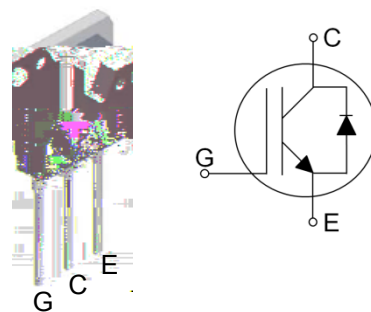


### Features

- 600V Field Stop Trench Technology
- High Speed Switching
- Low Conduction Loss
- Positive Temperature Coefficient
- Easy Parallel Operation
- Short Circuit Withstanding Time 5 s
- RoHS Compliant
- JEDEC Qualification

### Applications

UPS, Welder, Inverter, Solar



Device	Package	Marking	Remark
TGAN30N60FDR	TO-3PN	TGAN30N60FDR	RoHS

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Collector-Emitter Voltage	$V_{CES}$	600	V	
Gate-Emitter Voltage	$V_{GES}$	20	V	
Continuous Collector Current	$I_C$	$T_C = 25$	60	A
		$T_C = 100$	30	A
Pulsed Collector Current (Note 1)	$I_{CM}$	90	A	
Diode Continuous Forward Current	$I_F$	30	A	
Power Dissipation	$P_D$	$T_C = 25$	231	W
		$T_C = 100$	93	W
Operating Junction Temperature	$T_J$	-55 ~ 150		
Storage Temperature Range	$T_{STG}$	-55 ~ 150		
Maximum lead temperature for soldering purposes,	$T_L$	300		

Notes :

(1) Repetitive rating : Pulse width limited by maximum junction temperature

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Maximum Thermal resistance, Junction-to-Case	$R_{JC}$ (IGBT)	0.54	/W
Maximum Thermal resistance, Junction-to-Case	$R_{JC}$ (DIODE)	1.12	/W
Maximum Thermal resistance, Junction-to-Ambient	$R_{JA}$	40	/W

### Electrical Characteristics of the IGBT $T_C=25$ , unless otherwise noted

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
<b>OFF</b>						
Collector Emitter Breakdown Voltage	$BV_{CES}$	$V_{GE} = 0V, I_C = 1mA$	600	--	--	V
Zero Gate Voltage Collector Current	$I_{CES}$	$V_{CE} = 600V, V_{GE} = 0V$	--	--	1	mA
Gate Emitter Leakage Current	$I_{GES}$	$V_{CE} = 0V, V_{GE} = 20V$	--	--	250	nA
<b>ON</b>						
Gate Emitter Threshold Voltage	$V_{GE(TH)}$	$V_{GE} = V_{CE}, I_C = 30mA$	4.5	6.0	7.5	V
Collector Emitter Saturation Voltage	$V_{CE(SAT)}$	$V_{GE} = 15V, I_C = 30A, T_C = 25$	--	1.5	2.0	V
		$V_{GE} = 15V, I_C = 30A, T_C = 150$	--	1.8	--	V
<b>DYNAMIC</b>						
Input Capacitance	$C_{IES}$	$V_{CE} = 30V,$ $V_{GE} = 0V$ $f = 1MHz$	--	2000	--	pF
Output Capacitance	$C_{OES}$		--	135	--	pF
Reverse Transfer Capacitance	$C_{RES}$		--	80	--	pF
<b>SWITCHING</b> (Note 2)						
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400V, I_C = 30A$ $R_G = 10$ , $V_{GE} = 15V$ Inductive Load, $T_C = 25$	--	30	--	ns
Rise Time	$t_r$		--	45	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	135	--	ns
Fall Time	$t_f$		--	40	60	ns
Turn-On Switching Loss	$E_{ON}$		--	1.00	1.50	mJ
Turn-Off Switching Loss	$E_{OFF}$		--	0.66	0.99	mJ
Total Switching Loss	$E_{TS}$	--	1.66	2.49	mJ	
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400V, I_C = 30A$ $R_G = 10$ , $V_{GE} = 15V$ Inductive Load, $T_C = 150$	--	30	--	ns
Rise Time	$t_r$		--	50	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	145	--	ns
Fall Time	$t_f$		--	130	--	ns
Turn-On Switching Loss	$E_{ON}$		--	1.07	1.60	mJ
Turn-Off Switching Loss	$E_{OFF}$		--	1.00	1.50	mJ
Total Switching Loss	$E_{TS}$	--	2.07	3.10	mJ	
Total Gate Charge	$Q_g$	$V_{CC} = 400V, I_C = 30A$ $V_{GE} = 15V$	--	120	180	nC
Gate-Emitter Charge	$Q_{ge}$		--	12	18	nC
Gate-Collector Charge	$Q_{gc}$		--	70	105	nC
Short Circuit Withstanding Time	$t_{SC}$	$V_{CC} = 300V, V_{GE} = 15V, T_C = 125$	5	10	--	s

Notes :

(2) Not subject to production test verified by design/characterization



# IGBT Characteristics

Fig. 1 Output characteristics

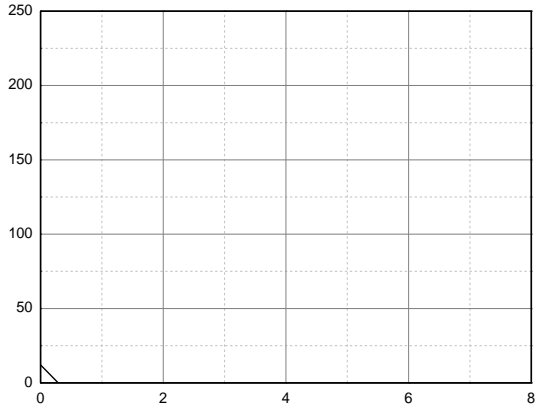


Fig. 2 Saturation voltage characteristics

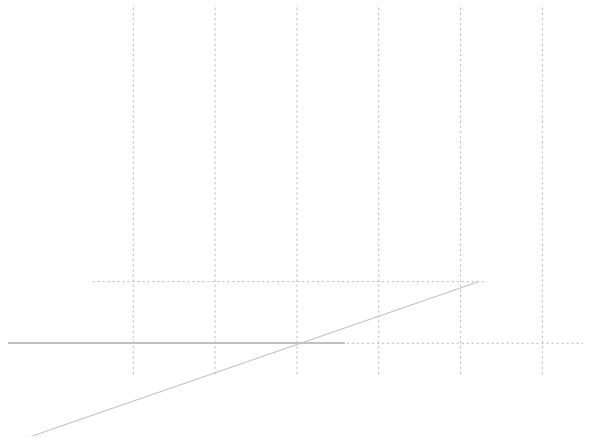


Fig. 3 Saturation voltage vs. collector current

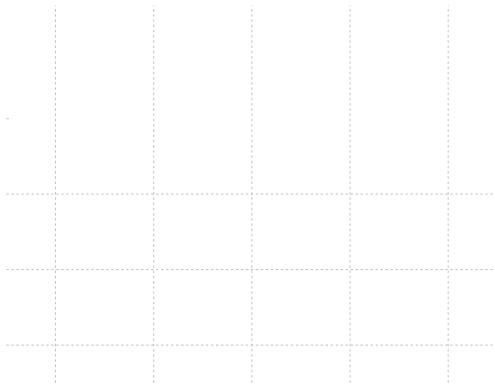


Fig. 4 Saturation voltage vs. gate bias

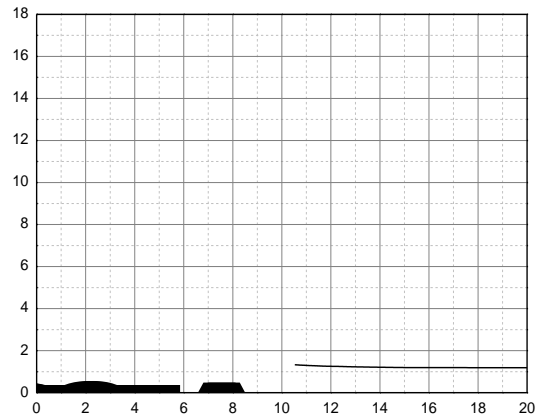


Fig. 5 Saturation voltage vs. gate bias

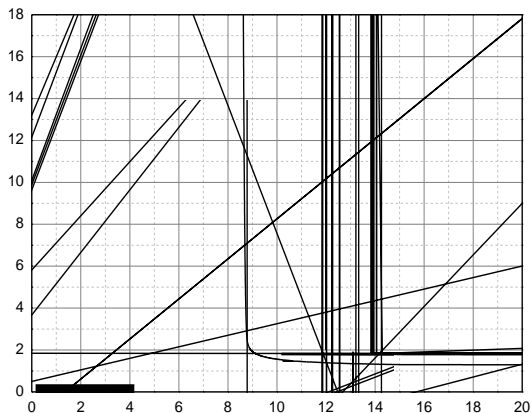
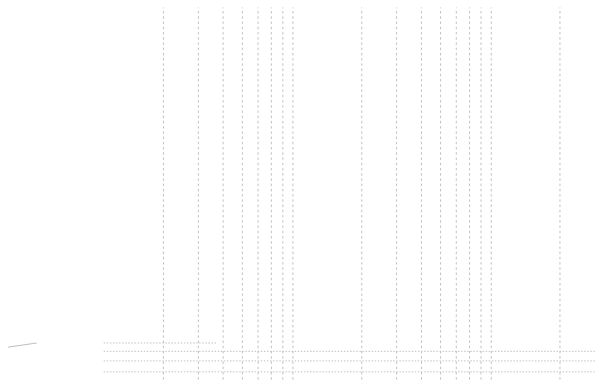


Fig. 6 Capacitance characteristics



**IGBT Characteristics**

Fig. 7 Turn-on time vs. gate resistor



Fig. 8 Turn-off time vs. gate resistor

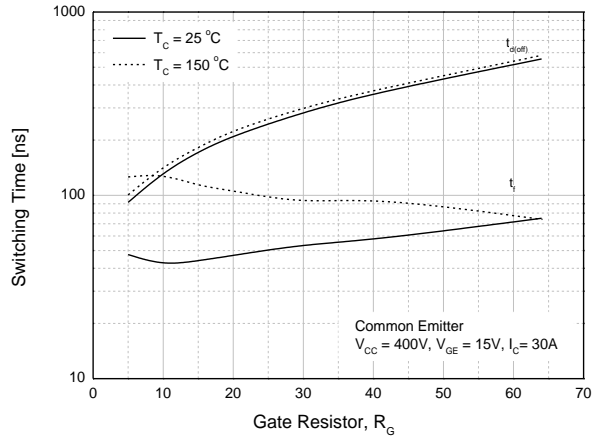


Fig. 9 Switching loss vs. gate resistor

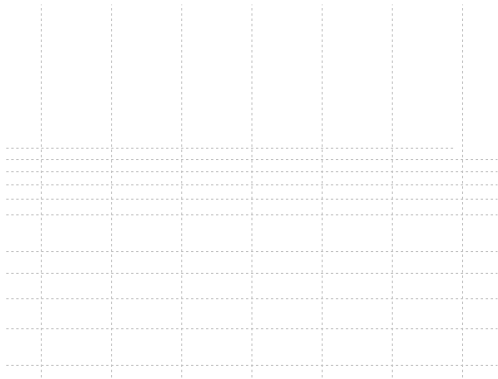


Fig. 10 Turn-on time vs. collector current

Fig. 11 Turn-off time vs. collector current

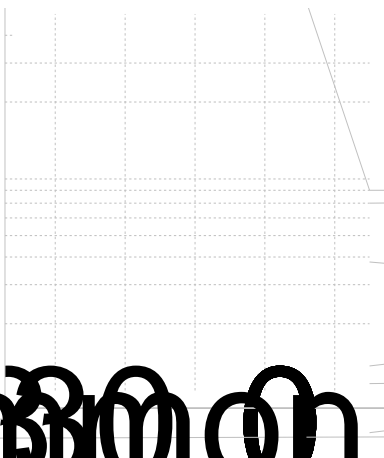
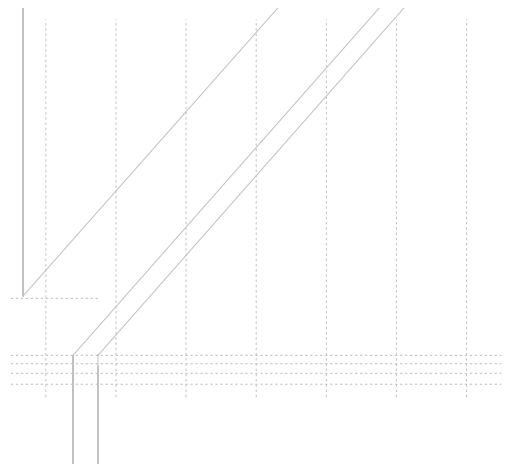


Fig. 12 Switching loss vs. collector current



# IGBT Characteristics

Fig. 13 Gate charge characteristics



Fig. 14 SOA

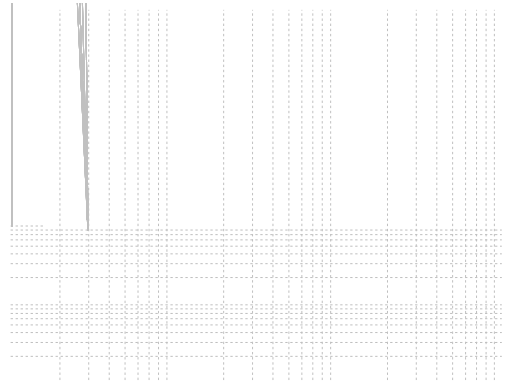


Fig. 15 RBSOA

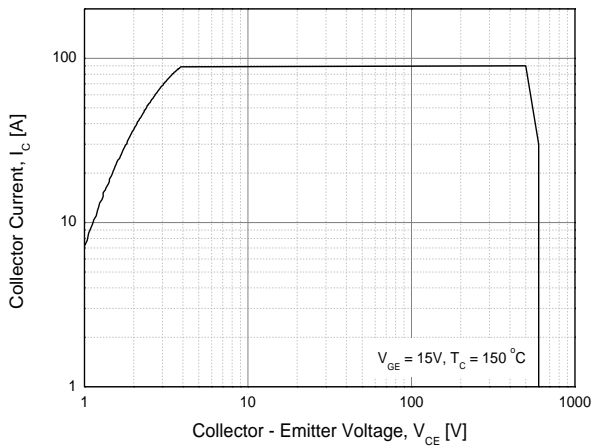


Fig. 16 Transient thermal impedance of IGBT

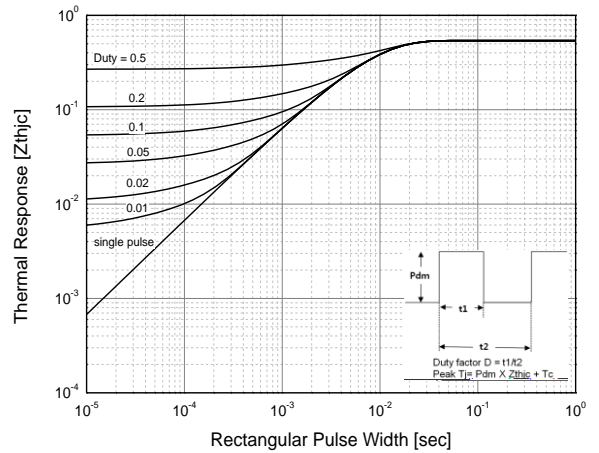
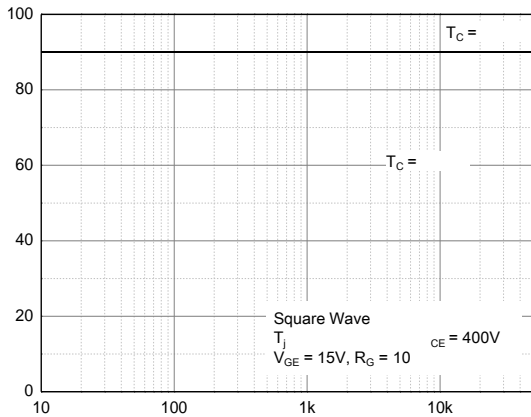


Fig. 17 Load Current vs. Frequency



## Diode Characteristics

Fig. 18 Conduction characteristics



Fig. 19 Reverse recovery current vs. forward current



Fig. 20 Reverse recovery charge vs. forward current

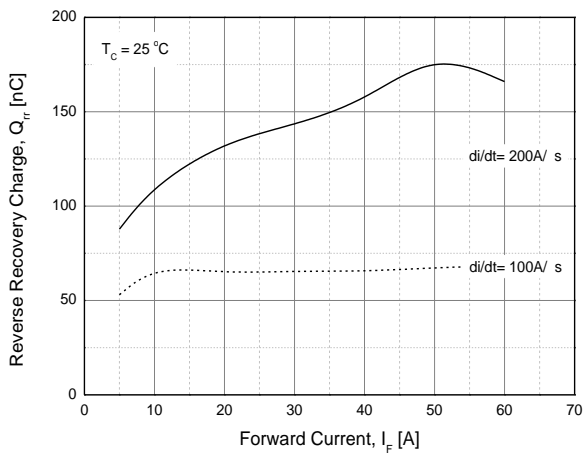
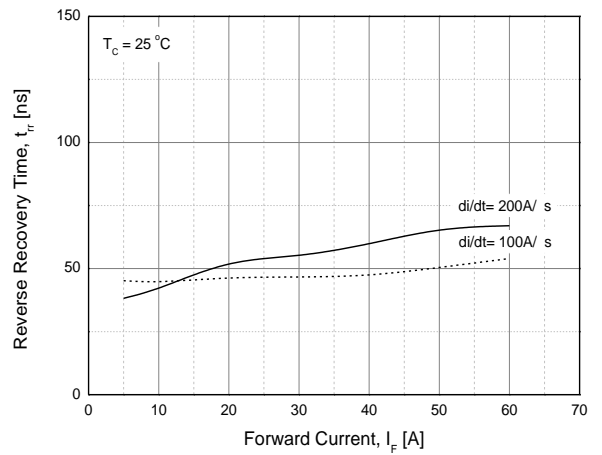
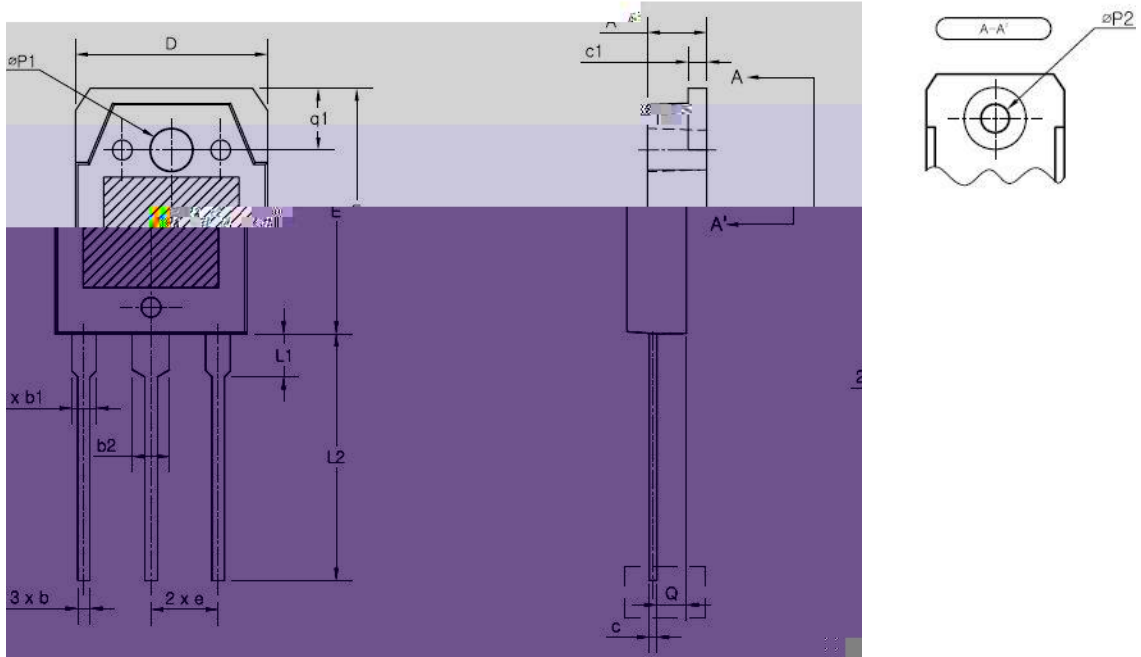


Fig. 21 Reverse recovery time vs. forward current



**TO-3PN MECHANICAL DATA**



SYMBOL	MIN	NOM	MAX
A	4.60	4.80	5.00
$\varnothing P1$	3.30	3.40	3.50
$\varnothing P2$	20.00	20.20	20.40

**Disclaimer**

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